

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		
CONVEYING PARTY DATA			
	Name	Execution Date	
	YASUHIRO KAJIKAWA	10/29/2020	
	HIROSHI SUGII	10/29/2020	
	YOSHINORI HIRAOA	10/29/2020	
RECEIVING PARTY DATA			
Name:	SENJU METAL INDUSTRY CO., LTD.		
Street Address:	23, SENJU-HASHIDO-CHO, ADACHI-KU		
City:	TOKYO		
State/Country:	JAPAN		
Postal Code:	120-8555		
PROPERTY NUMBERS Total: 1			
	Property Type	Number	
	Application Number:	17261072	
CORRESPONDENCE DATA			
Fax Number:	(412)471-4094		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	412-471-8815		
Email:	assignments@webblaw.com		
Correspondent Name:	THE WEBB LAW FIRM, P.C.		
Address Line 1:	ONE GATEWAY CENTER		
Address Line 2:	420 FT. DUQUESNE BLVD, SUITE 1200		
Address Line 4:	PITTSBURGH, PENNSYLVANIA 15222		
ATTORNEY DOCKET NUMBER:	7466-2005692		
NAME OF SUBMITTER:	BRYAN P. CLARK REG. #60465		
SIGNATURE:	/Bryan P. Clark/		
DATE SIGNED:	01/18/2021		
Total Attachments: 3			
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INTERNATIONAL

Application No. _____

Attorney Docket No. 7466-2005692

ASSIGNMENT

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in FLUX COMPOSITION, SOLDER PASTE, SOLDER JOINT AND SOLDER JOINING METHOD
(Invention Title)

☒ for which I have this day executed an application for a United States Patent (hereinafter "said application").

AND/OR

☐ for which an application for a United States Patent was filed on _____ (mm/dd/yyyy) and bears Application Number _____ (hereinafter "said application").

AND/OR

☒ for which an international patent application was filed under the Patent Cooperation Treaty on 08/01/2019 (mm/dd/yyyy), bearing Application No. PCT/JP2019/030153 (hereinafter "said application").

AND, WHEREAS, Senju Metal Industry Co., Ltd., a corporation of Japan, having a place of business at 23, Senju-Hashido-cho Adachi-ku, Tokyo 120-8555, Japan, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries, including rights of priority under the International Convention of Paris (1883) as amended, and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I hereby authorize and request any attorney associated with The Webb Law Firm, Customer No. 28289, to insert here in parentheses (Application No. 17/261,072, filed 08/01/2019) the filing date and application number of said application when known.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

INTERNATIONAL

Application No. _____

Attorney Docket No. 7466-2005692

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs, executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

1. FULL NAME OF ASSIGNOR:

RESIDENCE:

Yasuhiro KAJIKAWATochigi, JAPANEXECUTED this 27th day of October, 2020Yasuhiro KAJIKAWA

SIGNATURE

WITNESS:

2. FULL NAME OF ASSIGNOR:

RESIDENCE:

Hiroshi KAWASAKITokyo, JAPAN

EXECUTED this _____ day of _____, 2020

SIGNATURE

WITNESS:

☒ Checked Box indicates 1 additional page for inventor signatures.

INTERNATIONAL

Application No. _____

Attorney Docket No. 7466-2005592

3. FULL NAME OF ASSIGNOR:

Hiroshi SUGI

RESIDENCE:

Tachigi, JAPAN

EXECUTED this 29th day of October, 2020

Hiroshi Sugi

SIGNATURE

WITNESS:

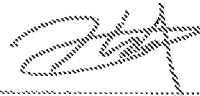
4. FULL NAME OF ASSIGNOR:

Yoshinori HIRAKA

RESIDENCE:

San Jose, California

EXECUTED this 29th day of October, 2020



SIGNATURE

WITNESS: